



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	10/823,280	Confirmation No.	4578
First Inventor	Saravuth Sirinorakul	Filing Date	April 12, 2004
Tech. Center/ Art Unit	2825	Examiner	Lalrinfamkim Hmar Malsawma
Title:	Method of Fabricating Semiconductor Chip Package Using Screen Printing of Epoxy on Wafer		
Docket No.:	NSE010 US	Customer No.:	34036

Santa Clara, California
April 4, 2005

Mail Stop Amendment
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office Action dated November 4, 2004, please amend the above-identified application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.